

Filename: PMP7828_BOM_REVA

Date: 3/7/13

Item	Designator	Description	Manufacturer	PartNumber	Quantity
1	AA1	Printed Circuit Board	TBD	Used in BOM Report	1
2	C1, C15, C29, C46	CAP, AL, 470uF, 25V, +/-20%, 0.08 ohm, SMD	Panasonic	EEE-FK1E471P	4
3	C2, C3, C4, C5, C16, C17, C18, C19, C30, C31, C38, C39	CAP, CERM, 10uF, 16V, +/-20%, X5R, 1206	TDK	C3216X5R1C106M	12
4	C6, C20, C32, C41	CAP, AL, 100uF, 16V, +/-20%, 0.024 ohm, SMD	Nippon Chemi-Con	APXE160ARA101MF80G	4
5	C7, C21, C33, C42	CAP, CERM, 2700pF, 100V, +/-5%, X7R, 0603	AVX	06031C272JAT2A	4
6	C8, C13, C22, C27, C34, C37, C43,	CAP, CERM, 0.1uF, 50V, +/-5%, X7R,	AVX	08055C104JAT2A	8
7	C9, C10, C11, C12, C23, C24, C25, C26, C35, C36, C44, C45	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1206	MuRata	GRM31CR60J107ME39L	12
8	C14, C28, C40, C48	CAP, CERM, 1000pF, 25V, +/-5%, C0G/NP0, 0603	MuRata	GRM1885C1E102JA01D	4
9	C49, C50, C51, C52, C53, C54, C55,	CAP, CERM, 4.7uF, 10V, +/-10%, X5R,	AVX	0805ZD475KAT2A	8
10	FID1, FID2, FID3, FID4, FID5, FID6	Fiducial mark. There is nothing to buy or mount.	N/A	N/A	6
11	H1, H2, H3, H4	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	B&F Fastener Supply	NY PMS 440 0025 PH	4
12	H5, H6, H7, H8	Standoff, Hex, 0.5"L #4-40 Nylon	Keystone	1902C	4
13	J1, J2, J3, J4	Standard Banana Jack, Uninsulated,	Keystone	575-8	4
14	L1, L3, L5, L8	Inductor, Shielded Drum Core, Ferrite, 330nH, 3.7A, 0.023 ohm, SMD	Coilcraft	LPS4012-331MLB	4
15	L2, L4	Inductor, Shielded Drum Core, Powdered Iron, 560nH, 27.5A, 0.0018 ohm, SMD	Vishay-Dale	IHLP4040DZERR56M01	2
16	L6	Inductor, Shielded INDUCTOR POWER 4.7UH 9.5A SMD	Vishay-Dale	IHLP4040DZER4R7M11	1
17	L7	Inductor, Shielded Drum Core, Powdered Iron, 2.2uH, 12A, 0.009 ohm, SMD	Vishay-Dale	IHLP4040DZER2R2M01	1
18	P1, P2, P3, P4, P5, P6, P7, P8, P9, P10, P11, P12, P13, P14, P15, P16, P17, P18, P19, P20, P21, P22, P23,	Terminal, Turret, TH, Double	Keystone	1502-2	25
19	R2, R6, R7, R16, R20, R21, R30, R34, R35, R43, R47, R48	RES, 0 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW06030000Z0EA	12
20	R3, R17, R31, R44	RES, 1.00 ohm, 1%, 0.25W, 1206	Vishay-Dale	CRCW12061R00FKEA	4
21	R4, R14, R18, R28, R42, R55	RES, 1.00k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-071KL	6
22	R8, R9, R22, R23, R36, R37, R49,	RES, 100k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW0603100KFKEA	8

23	R10, R24, R38, R51	RES, 499k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW0603499KFKEA	4
24	R11	RES, 133k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW0603133KFKEA	1
25	R12	RES, 665 ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-07665RL	1
26	R13, R27, R41, R54	RES, 187k ohm, 0.1%, 0.1W, 0603	Yageo America	RT0603BRD07187KL	4
27	R25	RES, 162k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW0603162KFKEA	1
28	R26	RES, 1.50k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW06031K50FKEA	1
29	R32, R45	RES, 1.74k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-071K74L	2
30	R39	RES, 35.7k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060335K7FKEA	1
31	R40	RES, 4.53k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW06034K53FKEA	1
32	R52	RES, 39.2k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060339K2FKEA	1
33	R53	RES, 2.00k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-072KL	1
34	T1, T2, T3, T4, T5, T6	Terminal 50A Lug	Panduit	CB35-36-CY	6
35	U1, U2	Scalable 2-Phase Synchronous Buck Controllers with Integrated FIC BUCK SYNC ADJ 30A 22SON	Texas Instruments	TPS53355DQPT	2
36	U3	Scalable 2-Phase Synchronous Buck Controllers with Integrated FIC BUCK SYNC ADJ 30A 22SON	Texas Instruments	TPS53318	1
37	U4	Scalable 2-Phase Synchronous Buck Controllers with Integrated FIC BUCK SYNC ADJ 30A 22SON	Texas Instruments	TPS53319	1
38	R1, R5, R15, R19, R29, R56	RES, 0 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW06030000Z0EA	0
39	R33, R46	RES, 1.00k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-071KL	0
40	R59	RES, 4.53k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW06034K53FKEA	0
41	R60	RES, 2.00k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-072KL	0

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